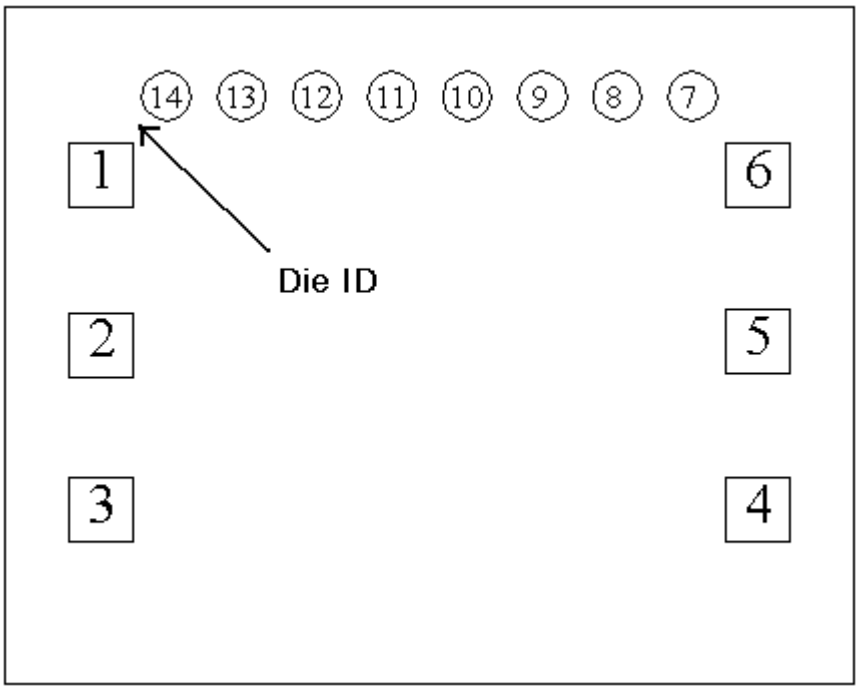
LM27-2PL MDA

±3°C ACCURATE, 145°C FACTORY PRESET THERMOSTAT WITH ACTIVE HIGH, PUSH/PULL OVERTEMPERATURE SHUTDOWN OUTPUT

May 17,2005

DIE LAYOUT (A-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM27A	Bond Pad Opening Size (min)	85μm x 85μm
Die Step	A	Bond Pad Metalization	Al_ 0.5%Cu
Physical Attributes		Passivation	PECVDOX+NITRIDE
Wafer Diameter	200mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1130μm x 902μm 44.5mils x 35.5mils	Back Side Connection	GND
Thickness	254μm Nominal		
Min Pitch	100μm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
HYST	1	-437	225	85	x	85
OS	2	-437	0	85	x	85
NC	3	-437	-220	85	x	85
V+	4	437	-220	85	x	85
GND	5	437	5	85	x	85
V_{TEMP}	6	437	225	85	x	85
NC	7	350	331	65	x	65
NC	8	250	331	65	x	65
NC	9	150	331	65	x	65
NC	10	50	331	65	x	65
NC	11	-50	331	65	x	65
NC	12	-150	331	65	x	65
NC	13	-250	331	65	x	65
NC	14	-350	331	65	x	65

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